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Automated **defect classification** system

VH Brecher, BL Paul, RW Hall, DM Parist, R ... - US Patent ..., 1996 - Google Patents
... describe a **wafer defect** detection and classi- fication system in "An Automated **Wafer** Inspection System ... **based** classifier that does not provide for uncer- tainty in the **defect** measures ... literature on using concepts of fuzziness as an uncertainty measure in classification applications ...
[Cited by 63](#) - [Related articles](#)

Automatic **defect classification** for semiconductor manufacturing

PB Chou, AR Rao, MC Sturzenbecker, FY Wu, ... - Machine Vision and ..., 1997 - Springer
... Patterned **wafer** inspection tools can optically detect **defects** less than 0.5 micron in di- ameter. ... Much of the excitement of ADC arises from the challenge of the classification technology ... be constructed by representing their knowledge in terms of **rules** that relate **defect** attributes to ...
[Cited by 48](#) - [Related articles](#) - [Sci Direct](#) - [All 3 versions](#)

Model-based clustering for integrated circuit yield enhancement

JY Hwang, W Kuo - European Journal of Operational Research, 2007 - Elsevier
... The curvilinear feature is one of the typical patterns observed on **wafer defect** maps with ... Approximate modeling of curvilinear **defect** patterns with the bivariate normal **distribution** may ... information about the characteristics of clusters and decrease the classification capability [14]. ...
[Cited by 11](#) - [Related articles](#) - [All 7 versions](#)

Monitoring **wafer** map data from integrated circuit fabrication processes for spatially clustered **defects**

MH Hansen, VN Nair, DJ Friedman - Technometrics, 1997 - JSTOR
... In general, clusters of **defects** can be **classified** as either particle or process related, with particle-related clus- ters being assignable to individual machines and process- related clusters being ... MONITORING **WAFER** MAP DATA FOR SPATIALLY CLUSTERED **DEFECTS** ...
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[PDF] Recent progress in industrial machine vision

G Montad, JLC Sanz - International Journal of Robotics and Automation, 1993 - mva-org.jp
... patches. The **likelihood** of the presence of the match of a fea- ture point in the other image should be high. It ... circuited region. To obtain statistical information on the **wafer**, a **defect** classification circuit can be used. This circuit ...
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[mva-org.jp \[PDF\]](#)

[PDF] Determining composition of grain mixtures by texture **classification based** on feature **distributions**

T Ojala, M Pietikäinen, J Nisula - International Journal of Pattern ..., 1996 - Citeseer
... The proposed applications include, for example, the detection and identification of surface **defects** on metal surfaces, textiles or semiconductor **wafers**, the assessment of ... This procedure was repeated for all samples and the classification error rate was determined as the ...
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[psu.edu \[PDF\]](#)

A cost-based heuristic for statistically determining sampling frequency in a **wafer** fab

CF Chien, SC Hsu, S Peng, CH Wu - 2000 - 140.114.72.28
... However, 100% inspection is practiced at **wafer** sort to **classify** dice, we assume that there is ... as well as the optimal allocation of inspection capacity depends on the **defect** variability ... needed for extending the proposed method to deal with the whole in-line **wafer** sampling strategy ...
[Cited by 4](#) - [Related articles](#) - [View as HTML](#) - [All 2 versions](#)

A model-based clustering approach to the recognition of the spatial **defect** patterns produced during semiconductor fabrication


T Yuan, W Kuo - IIE Transactions, 2008 - informaworld.com
... The indexing values for classification, the y_i in the classification **likelihood** function (2), satisfy $y_i = k$ if $z_{ik} = 1$. In the parameter estimation ... In the simulation studies, the diameter of the **wafers** is 20 cm. ... The intensity function used in the global **defect** generation is quadratic, that is ...
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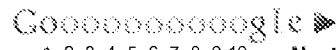
A hybrid fuzzy-statistical clustering approach for estimating the time of changes in fixed and variable sampling control charts

A Alaeiddini, M Ghazvini, MA Nayeri - Information Sciences, 2009 - Elsevier
... and more rational than revised C-charts which are used in monitoring **wafer defects** during IC ... [4] use expert technology to select unstable slicing machines to control **wafer** slicing quality ... (2) Similar to clustering methods, change-point models are used to **classify** patterns: almost ...
[Cited by 3](#) - [Related articles](#) - [All 2 versions](#)

Spatial **defect** pattern recognition on semiconductor **wafers** using model-based clustering and Bayesian inference

T Yuan, W Kuo - European Journal of Operational Research, 2006 - Elsevier
... Section 2 describes the mixture model used to describe the **defect distributions** on the **wafers**. ... In both approaches, the locations s_i are regarded as incomplete data and the complete data are considered to be (s_i, z_i) , where the classification variables $z_i = (z_{i0}, z_{i1}, \dots, z_{iG})$, $i \dots$
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